AMENDMENTS TO THE SPECIFICATION

Please amend the specification as follows:

On page 1, after the title, please insert the following:

-This application is a continuation of Application Serial No. 09/840,291 filed April 24, 2001, 18(3/9/04) 2001:
NOW U.S. PATENT 6,623,895, which is a CIP of 09/562,443 filed the 18/9/04 2001:05/01/2000 NOW ABDONED,

AL(3/9/04)

HYBRID PHASE-SHIFT MASK

- This application is a continuation-in-part-of-application Serial No. 09/562,443, which was filed on May 1, 2000.

Field Of The Invention

The present invention relates to the design of photomasks ("masks") for use in lithography, and more particularly, to the use of a hybrid mask which provides for the formation of both phase-shifted and non-phase-shifted features with a single exposure.

The present invention also relates to the use of such a mask in a lithographic apparatus, comprising for example:

- a radiation system for supplying a projection beam of radiation;
- a mask table for holding the mask;
- 10 a substrate table for holding a substrate; and
 - a projection system for projecting at least part of a pattern on the mask onto a target portion of the substrate.

Background Of The Invention

15

20

25

5

Lithographic apparatus can be used, for example, in the manufacture of integrated circuits (ICs). In such a case, the mask may contain a circuit pattern corresponding to an individual layer of the IC, and this pattern can be imaged onto a target portion (e.g. comprising one or more dies) on a substrate (silicon wafer) that has been coated with a layer of radiation-sensitive material (resist). In general, a single wafer will contain a whole network of adjacent target portions that are successively irradiated via the projection system, one at a time. In one type of lithographic projection apparatus, each target portion is irradiated by exposing the entire mask pattern onto the target portion in one go; such an apparatus is commonly referred to as a wafer stepper. In an alternative apparatus —commonly referred to as a step-and-scan apparatus — each target portion is irradiated by progressively scanning the mask pattern under the projection beam in a given reference direction (the "scanning" direction) while synchronously scanning the substrate table parallel or anti-parallel to this direction; since, in general, the projection system will have a magnification factor M (generally < 1), the speed V at which the substrate table is scanned will be a factor M times that at which the mask table is scanned. More